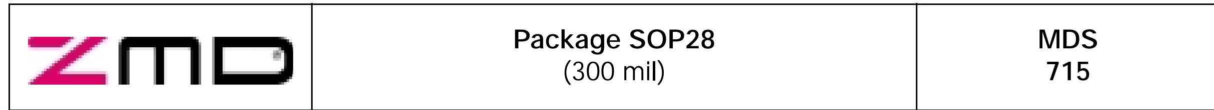


# Package SOP28 (300 mil)

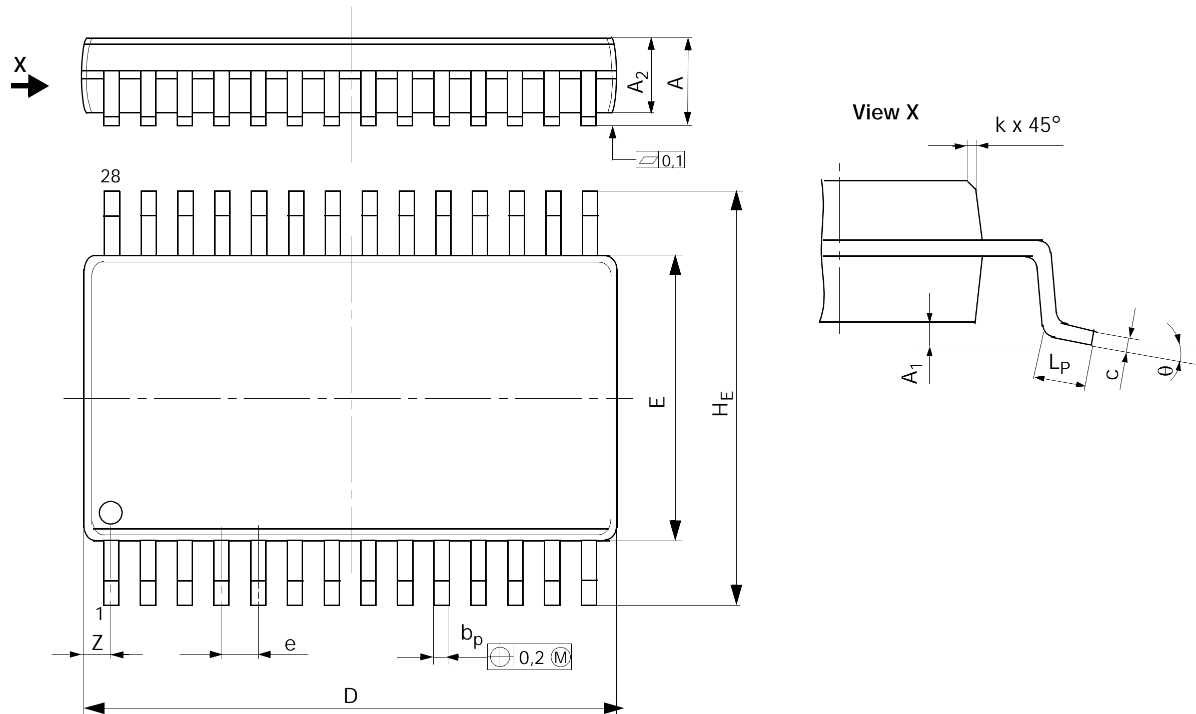
**MDS 715**

Supersedes
Edition 06.92
1. Amendment 09.93

Dimensions in millimetres

Based on IEC 191-2Q: Type 075E06 B

## 1 Dimensions




| Dimensions of Sub-Group B1 | |
|---|---|
| $A_{max}$ | 2,65 |
| $b_{Pmin}$ | 0,35 |
| $b_{Pmax}$ | 0,49 |
| $e_{nom}$ | 1,27 |
| $H_{Emin}$ | 10,00 |
| $H_{Emax}$ | 10,65 |
| $L_{Pmin}$ | 0,40 |
| $Z_{max}$ | 0,81 |

| Dimensions of Sub-Group C1 | |
|---|---|
| $A_{min}$ | 2,35 |
| $A_{1min}$ | 0,10 |
| $A_{1max}$ | 0,30 |
| $A_{2min}$ | 2,25 |
| $A_{2max}$ | 2,45 |
| $c_{min}$ | 0,23 |
| $c_{max}$ | 0,32 |
| $D_{min}$* | 17,70 |
| $D_{max}$* | 18,10 |
| $E_{min}$* | 7,40 |
| $E_{max}$* | 7,60 |
| $k_{min}$ | 0,25 |
| $\theta_{min}$ | 0° |
| $\theta_{max}$ | 8° |

* without mold-flash

| | |
|---|---|
| **2 Weight** | ≤ 0,8 g |
| **3 Package Body Material** | Low Stress Epoxy |
| **4 Lead Material** | FeNi-Alloy or Cu-Alloy |
| **5 Lead Finish** | solder plating |
| **6 Lead Form** | Z-bends |

| Zentrum Mikroelektronik Dresden AG | | |
|---|---|---|
| Editor: signed Schoder | Date: 13.11.95 | Doc-No. QS-000715-HD-02 |
| Check: signed Wilde | Quality: signed Lorenz | |

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